



SPECIFICATIONS OF LCD MODULE

Features

- 128*64 dots matrix graphic display
- Controller IC NT7108 or equivalence
- Easy interface with 8-bit MPU
- +5V DC power supply
- STN LCD yellow-green, positive display, transflective type.
- 1/64 duty
- 6 O'clock viewing direction
- Array LED backlight, yellow-green color
- Built-in negative voltage supply -5V V_{EE}
- Operating temperature range -20°C to 70°C

Mechanical Specifications (Unit: mm)



PIN	1	2	3	4	5	6	7	8	9	10
SIGNAL	VSS	VDD	V0	D/I	R/W	Е	DB0	DB1	DB2	DB3
PIN	11	12	13	14	15	16	17	18	19	20
SIGNAL	DB4	DB5	DB6	DB7	CS1	CS2	RES	VEE	A(+)	K(-)

Temperature Characteristics

Parameter	Symbol	Rating	Unit
Operating temperature	T _{OP}	-20 ~ +70	°C
Storage temperature	T _{ST}	$-30 \sim +80$	°C

Block diagram



Electro-Optical characteristics



STN LCD (Super twisted nematic)

 $(T_A=25^{\circ}C, V_{DD}=5.0V\pm0.25V)$

ITEM	SYMBOL	CONDITION	MIN.	TYP.	MAX.	UNIT
Viewing Angle	<u>θ2-θ1</u> φ	Cr = 2.0	70 -90	-	+90	deg.
Contrast Ratio	Cr	$\begin{array}{c} \theta=20^{\mathrm{o}} \\ \phi=0^{\mathrm{o}} \end{array}$	-	8	-	-
Response Time (rise)	t _R	$\begin{array}{c} \theta=20^{\mathrm{o}} \\ \phi=0^{\mathrm{o}} \end{array}$	-	200	280	ms
Response Time (fall)	t _F	$\theta=20^{\circ}$ $\phi=0^{\circ}$	-	220	300	ms

Backlight Characteristics

Parameter	Symbol	Conditions	Min.	Тур.	Max.	Unit
Backlight supply voltage	$V_{\rm F}$	Input by pin19(+)&20(-)	-	4.8	5.0	V
Backlight supply current	$I_{\rm F}$	$V_F = 5.0 V$	-	120	200	mA

Interface Pin Connections

Pin No.	Symbol	I/O Type	Description			
1	V _{SS}	Supply	Ground			
2	V _{DD}	Supply	Power supply			
3	V_0	Supply	LCD driver supply voltage			
			Data or Instruction.			
4	RS		RS = H DB<0:7>: Display RAM data RS = L DB<0:7>: Instruction data			
			Read or Write			
5	R/W		RW Description H Data appears at DB[0:7] and can be read by the CPU while E= H CS1B=L, CS2B=L and CS3=H. L Display data DB[0:7] can be written at falling edge of E when CS1B=L, CS2B=L and CS3=H.			
			Enable signal			
6	E		 E Description H Read data in DB[7:0] appears while E= "High". L Display data DB[7:0] is latched at falling edge of E. 			
7~14	DB0~ DB7	I/O	Data bus [0~7] Bi-directional data bus			
15	CS1		Chip selection			
16	CS2	I	When CS1=L,CS2=H, select IC1 When CS1=H,CS2=L, select IC2			
			Reset signal.			
17	RES	Ι	 When RES=L [1] ON/OFF register becomes set by 0.(display off) [2] display start line register becomes set by 0 (Z-address 0 set, display from line 0) [3] After releasing reset, this condition can be changed only by instruction. 			
18	V _{EE}	Power	VEE is connected by the same voltage.			
19	A(LED+)		Power for backlight (Anode)			
20	K(LED-)		Power for backlight (Cathode)			

Contrast adjust circuit



V_{DD-}V₀: LCD Driving voltage VR: 10k~20k

Parameter	Symbol	Rating	Unit	Note
Operating voltage	V _{DD}	-0.3 ~ +7.0	V	*1
Supply voltage	V_{EE}	$V_{DD} 15.0 \sim V_{DD} \text{+-} 0.3$	V	*4
	VB	$\text{-}0.3 \sim V_{DD}\text{+}0.3$	V	*1,2
Driver supply voltage	V _{LCD}	$V_{EE}\text{-}0.3 \sim V_{DD}\text{+}0.3$	V	*3,4

Electrical Absolute Maximum Ratings (NT7107)

*Notes:

- *1. Based on $V_{SS} = 0V$
- *2. Applies to input terminals and I/O terminals at high impedance. (Except V0L, V1L, V4L, and V5L)
- *3. Applies to V0L, V1L, V4L, and V5L.
- *4. Voltage level: $V_{DD} \ge V_0 \ge V_1 \ge V_2 \ge V_3 \ge V_4 \ge V_5 \ge V_{EE}$

DC Electrical Characteristics (NT7107)

$(V_{DD} = 4.5 \text{ to } 5.5 \text{V})$	$V_{SS}=0V, V_{DD}-V_{EE}=8\sim17V, Ta=-20 \text{ to } +70^{\circ}C)$
() DD	199 0 1, 199 1 EE 0 17 1, 100 20 0 0 70 0)

Item	Symbol	Condition	Min.	Тур.	Max.	Unit	Note
Operating voltage	V _{DD}	-	4.5	-	5.5		
Innut voltage	V _{IH}	-	$0.7_{\rm VDD}$	-	V _{DD}		*1
Input voltage	V _{IL}	-	Vss	-	$0.3 V_{\text{DD}}$	V	*1
autout valta aa	V _{OH}	I_{OH} = -0.4mA	VDD-0.4	-	-		*2
output voltage	V _{OL}	$I_{OL}=0.4mA$	-	-	0.4		*2
Input leakage current	I _{LKG}	$V_{IN} = V_{DD} \sim V_{SS}$	-1.0	-	+1.0	μA	*1
OSC Frequency	fosc	Rf=47k $\Omega \pm 2\%$	315	450	585	1	кНz
OSC Frequency	lose	Cf=20pF \pm 5%	515			KIIZ	
On Resistance	R _{ONS}	V_{DD} - V_{EE} =17V	-	_	1.5	kΩ	
(Vdiv-Ci)	RONS	Load current $\pm 150 \mu A$			1.5	K	
	I _{DD1}	Master mode	-	-	1.0		*3
Operating current		1/128 Duty				-	
	I _{DD2}	Master mode 1/128 Duty	-	-	0.2	mA	*4
Supply Current	IEE	Master mode	_	_	0.1		*5
Supply Culton	IEE	1/128 Duty	_	-	0.1		5
Operating fop1		Master mode External Duty	50	-	600	1	кНz
Frequency fop2		Slave mode	0.5	-	1500		λΠΖ

Notes

- *1. Applies to input terminals FS, DS1, DS2, CR, SHL, MS and PCLK2 and I/O terminals DIO1, DIO2, M, and CL2 in the input state.
- *2. Applies to output terminals CLK1, CLK2 and FRM and I/O terminals DIO1, DIO2, M, and CL2 in the output state.
- *3. This value is specified about current flowing through V_{SS} .

Internal oscillation circuit: Rf=47kΩ, Cf=20pF

Each terminal of DS1, DS2, FS, SHL, and MS is connected to V_{DD} and out is no load.

*4. This value is specified about current flowing through V_{SS} .

Each terminal is DS1, DS2, FS, SHL, PCLK2 and CR is connected to VDD, MS is connected to VSS, and CL2,

M, DIO1 is external clock.

*5. This value is specified about current flowing through V_{EE} , Don't connect to V_{LCD} (V1~V5).

Electrical Absolute Maximum Ratings (NT7108)

Parameter	Symbol	Rating	Unit	Note
Operating voltage	V_{DD}	-0.3 ~ +7.0	V	*1
Supply voltage	V_{EE}	$V_{DD}\text{-}19.0 \sim V_{DD}\text{+}0.3$	V	*4
	V_B	$\text{-}0.3 \sim V_{DD}\text{+}0.3$	V	*1,3
Driver supply voltage	V _{LCD}	$V_{EE}\text{-}0.3 \sim V_{DD}\text{+}0.3$	V	*2

*Notes:

- *1. Based on $V_{SS} = 0V$
- *2. Applies the same supply voltage to V_{EE} . $V_{LCD}=V_{DD}-V_{EE}$.
- *3. Applies to M, FRM, CLK1, CLK2, CL, RESETB, ADC, CS1B, CS2B, CS3, E, R/W, RS and DB0~DB7.
- *4. Applies V0L,V2L,V3L and V5L.

Voltage level: $V_{DD} \ge V0 \ge V1 \ge V2 \ge V3 \ge V4 \ge V5 \ge V_{EE}$

DC Electrical Characteristics (NT7108)

 $(V_{DD}=4.5 \text{ to } 5.5 \text{V}, V_{SS}=0 \text{V}, V_{DD}-V_{EE}=8\sim17 \text{V}, Ta=-20 \text{ to } +70 ^{\circ}\text{C})$

Item	Symbol	Condition	Min.	Тур.	Max.	Unit	Note
Operating voltage	V_{DD}	-	4.5	-	5.5		
In most III als and the size	V _{IH1}	-	$0.7_{\rm VDD}$	-	V _{DD}		*1
Input High voltage	V _{IH2}	-	2.0	-	V _{DD}		*2
т. т. 1.	V _{IL1}	-	0	-	$0.3 V_{DD}$	V	*1
Input Low voltage	V _{IL2}	-	0	-	0.8		*2
Output High Voltage	V _{OH}	I _{OH} = -0.2mA	2.4	-	-		*3
Output Low Voltage	V _{OL}	$I_{OL}=1.6mA$	-	-	0.4		*3
Input leakage current	I _{LKG}	$V_{IN} = V_{SS} \sim V_{DD}$	-1.0	-	+1.0	μA	*4
Three-state (OFF) Input Current	Itsl	$V_{IN} \!\!= V_{SS} \sim V_{DD}$	-5.0	-	5.0		*5
Driver Input leakage current	Idil	$V_{IN} = V_{EE} \sim V_{DD}$	-2.0		2.0		*6
On Resistance (Vdiv-Ci)	R _{ONS}	V_{DD} - V_{EE} =15V Load current±100 μ A	-	-	7.5	kΩ	*8
	I _{DD1}	During Display	-	-	0.1		*7
Operating current	I _{DD2}	During Access Access Cycle=1MHz	-	-	0.5	mA	*7

Notes

- *1. CL, FRM, M, RSTB, CLK1, CLK2
- *2. CS1B, CS2B, CS3, E, R/W, RS, DB0~DB7
- *3. DB0~DB7
- *4. Except DB0~DB7
- *5. DB0~DB7 at high impedance
- *6. V0, V1, V3, V3, V4, V5

- *7. 1/64 duty, FCLK=250KHZ, Frame Frequency=70HKZ, Output: No Load
- *8. VDD-VEE=15.5V

 $V0L>V2L>=V_{DD}-2/7(V_{DD}-V_{EE})>V3L=V_{EE}+2/7(V_{DD}-V_{EE})>V5L$

MPU Interface

Characteristic	Symbol	Min	Тур	Max	Unit
E Cycle	t _C	1000	-	-	
E High Level Width	t _{WH}	450	-	-	
E Low Level Width	t _{WL}	450	-	-	
E Rise Time	t _R	-	-	25	
E Fall Time	t _F	-	-	25	
Address Set-Up Time	t _{ASU}	140	-	-	ns
Address Hold Time	t _{AH}	10	-	-	
Data Set-Up Time	t _{SU}	200	-	-	
Data Delay Time	t _D	-	-	320	
Data Hold Time (Write)	t _{DHW}	10	-	-	
Data Hold Time (Read)	t _{DHR}	20	-	-	





Operating Principles & Methods

1. I/O Buffer

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Input buffer controls the status between the enable and disable of chip. Unless the CS1B to CS3 is in active mode, Input or output of data and instruction does not execute. Therefore internal state is not change. But RSTB and ADC can operate regardless CS1B-CS3.

2. Input register

Input register is provided to interface with MPU which is different operating frequency. Input register stores the data temporarily before writing it into display RAM.

When CS1B to CS3 are in the active mode, R/W and RS select the input register. The data from MPU is written into input register. Then writing it into display RAM. Data latched for falling of the E signal and write automatically into the display data RAM by internal operation.

3. Output register

Output register stores the data temporarily from display data RAM when CS1B, CS2B and CS3 are in active mode and R/W and RS=H, stored data in display data RAM is latched in output register. When CS1B to CS3 is in active mode and R/W=H, RS=L, status data (busy check) can read out.

To read the contents of display data RAM, twice access of read instruction is needed. In first access, data in display data RAM is latched into output register. In second access, MPU can read data which is latched. That is to read the data in display data RAM, it needs dummy read. But status read is not needed dummy read.

RS	R/W	Function					
т	L	Instruction					
L	Н	Status read (busy check)					
L L		Data write (from input register to display data RAM)					
Н	Н	Data read (from display data RAM to output register)					

4. Reset

The system can be initialized by setting RSTB terminal at low level when turning power on, receiving instruction from MPU. When RSTB becomes low, following procedure is occurred.

1. Display off

2. Display start line register become set by 0.(Z-address 0)

While RSTB is low, No instruction except status read can by accepted. Therefore, execute other instructions after making sure that DB4= (clear RSTB) and DB7=0 (ready) by status read instruction.

The conditions of power supply at initial power up are shown in table 1.

Item	Symbol	Min	Тур	Max	Unit
Reset Time	t _{RS}	1.0	-	-	us
Rise Time	t _R	-	-	200	ns



5. Busy flag

Busy flag indicates that NT7108 is operating or no operating. When busy flag is high, NT7108 is in internal operating.

When busy flag is low, NT7108 can accept the data or instruction.

DB7indicates busy flag of the NT7108.



6. Display On/Off Flip-Flop

The display on/off flip-flop makes on/off the liquid crystal display. When flip-flop is reset (logical low), selective voltage or non selective voltage appears on segment output terminals. When flip-flop is set (logic high), non selective voltage appears on segment output terminals regardless of display RAM data.

The display on/off flip-flop can changes status by instruction. The display data at all segment disappear while RSTB is low.

The status of the flip-flop is output to DB5 by status read instruction. The display on/off flip-flop synchronized by CL signal.

7. X Page Register

X page register designates pages of the internal display data RAM. Count function is not available. An address is set by instruction.

8. Y address counter

Y address counter designates address of the internal display data RAM. An address is set by instruction and is increased by 1 automatically by read or write operations of display data.

9. Display Data RAM

Display data RAM stores a display data for liquid crystal display. To indicate on state dot matrix of liquid crystal display, write datra1. The other way, off state, writes 0.

Display data RAM address and segment output can be controlled by ADC signal.

ADC=H => Y-address 0: S1~Y address 63: S64

ADC=L => Y-address 0: S64~Yaddress 63: S1

ADC terminal connect the V_{DD} or V_{SS}.

10. Display Start Line Register

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The display start line register indicates of display data RAM to display top line of liquid crystal display. Bit data (DB<0.5>) of the display start line set instruction is latched in display start line register. Latched data is transferred to the Z address counter while FRM is high, presetting the Z address counter. It is used for scrolling of the liquid crystal display screen.

Display Control Instruction

The display control instructions control the internal state of the NT7108. Instruction is received from MPU to NT7108 for the display control. The following table shows various instructions.

Instruction	RS	RW	DB7	DB6	DB5	DB4	DB3	DB2	DB1	DB0	Function
Read Display Date	1	1				Read	l data				Reads data (DB [7:0]) from display data RAM to the data bus.
Write Display Date	1	0		Write data					Writes data (DB [7:0]) into the DDRAM. After writing instruction, Y address is incriminated by 1 automatically		
Status Read	0	1	Busy	0	ON/ OFF	Re- set	0	0	0	0	Reads the internal status BUSY 0: Ready 1: In operation ON/OFF 0: Display ON 1: Display OFF RESET 0: Normal 1: Reset
Set Address (Y address)	0	0	0	1			Y addres	s (0~63))		Sets the Y address at the column address counter
Set Display Start Line	0	0	1	1		Dis	play star	t line (0-	~63)		Indicates the Display Data RAM displayed at the top of the screen.
Set Address (X address)	0	0	1	0	1	1 1 1 Page (0~7)		Sets the X address at the X address register.			
Display On/off	0	0	0	0	1	1	1	1	1	0/1	Controls the display ON or OFF. The internal status and the DDRAM data is not affected. 0: OFF, 1: ON

1. Display On/Off

The display data appears when D is 1 and disappears when D is 0.

Though the data is not on the screen with D=0, it remains in the display data RAM.

Therefore, you can make it appear by changing D=0 into D=1.

			-	-	-	-	-			
F	RS	R/W	DB7	DB6	DB5	DB4	DB3	DB2	DB1	DB0
F	0	0	0	0	1	1	1	1	1	D

2. Set Address (Y Address)

Y address (AC0~AC5) of the display data RAM is set in the Y address counter.

An address is set by instruction and increased by 1 automatically by read or write operations of display data.

RS	R/W	DB7	DB6	DB5	DB4	DB3	DB2	DB1	DB0
0	0	0	1	AC5	AC4	AC3	AC2	AC1	AC0

3. Set Page (X Address)

X address (AC0~AC2) of the display data RAM is set in the X address register.

Writing or reading to or from MPU is executed in this specified page until the next page is set.

RS	R/W	DB7	DB6	DB5	DB4	DB3	DB2	DB1	DB0
0	0	1	0	1	1	1	AC2	AC1	AC0

4. Display Start Line (Z Address)

Z address (AC0~AC5) of the display data RAM is set in the display start line register and displayed at the top of the screen.

When the display duty cycle is 1/64 or others $(1/32 \sim 1/64)$, the data of total line number of LCD screen, from the line specified by display start line instruction, is displayed.

RS	R/W	DB7	DB6	DB5	DB4	DB3	DB2	DB1	DB0
0	0	1	1	AC5	AC4	AC3	AC2	AC1	AC0

5. Status Read

RS	R/W	DB7	DB6	DB5	DB4	DB3	DB2	DB1	DB0
1	0	BUSY	0	ON/OFF	RESET	0	0	0	0

• BUSY

When BUSY is 1, the Chip is executing internal operation and no instructions are accepted.

When BUSY is 0, the Chip is ready to accept any instructions.

• ON/OFF

When ON/OFF is 1, the display is on.

When ON/OFF is 0, the display is off.

• RESET

When RESET is 1, the system is being initialized.

In this condition, no instructions except status read can be accepted.

When RESET is 0, initializing has finished and the system is in the usual operation condition.

6. Write Display Data

Write data (D0~D7) into the display data RAM.

After writing instruction, Y address is increased by 1 automatically.

RS	R/W	DB7	DB6	DB5	DB4	DB3	DB2	DB1	DB0
1	0	D7	D6	D5	D4	D3	D2	D1	D0

7. Read Display Data

Reads data (D0~D7) from the display data RAM.

After reading instruction, Y address is increased by 1 automatically.

RS	R/W	DB7	DB6	DB5	DB4	DB3	DB2	DB1	DB0
1	1	D7	D6	D5	D4	D3	D2	D1	D0

Quality Specifications

Cosmetic inspection

The inspection should be performed in using 20W x 2 fluorescent lamps. Distance between LCM and fluorescent lamps should be 100 cm or more. Distance between LCM and inspector eyes should be 25 cm or more. Viewing direction for inspection is 35° from vertical against LCM.



Definition of zone:



A Zone: Active display area (minimum viewing area).

B Zone: Non-active display area (outside viewing area).

Specification of quality assurance

AQL inspection standard

Sampling method: MIL-STD-105E, Level II, single sampling

Defect classification

	Classify	Item	Note	AQL
Major	Display state	Short or open circuit	1	0.65
		LC leakage		
		Flickering		
		No display		
		Wrong viewing direction		
		Contrast defect (dim, ghost)	2	
		Backlight	1,8	
	Non-display	Flat cable or pin reverse	10	
		Wrong or missing component	11	
Minor	Display	Background color deviation	2	1.0
	state	Black spot and dust	3	
		Line defect, Scratch	4	
		Rainbow	5	
		Chip	6	
		Pin hole	7	
		Protruded	12	
	Polarizer	Bubble and foreign material	3	
	Soldering	Poor connection	9	
	Wire	Poor connection	10	
	TAB	Position, Bonding strength	13	

Note on defect classification

No.	Item	Criterion
1	Short or open circuit	Not allow
	LC leakage	
	Flickering	
	No display	
	Wrong viewing direction	
	Wrong Back-light	
2	Contrast defect	Refer to approval sample
	Background color deviation	
3	Point defect, Black spot, dust (including Polarizer) $\phi = (X+Y)/2$	PointAcceptable Qty.Size $\phi \leq 0.10$ Disregard $0.10 < \phi \leq 0.15$ 2 $0.15 < \phi \leq 0.25$ 1 $\phi > 0.25$ 0
4	Line defect, Scratch	$\begin{array}{c c} & & & \\ & & & \\ \hline & & \\ L & & \\ L & & \\ & & \\ L & & \\ \hline & & \\ \hline & & \\ & & \\ \hline & & \\ \hline & & \\ & & \\ \hline \\ \hline$
5	Rainbow	Not more than two color changes across the viewing area.

No	Item	Criterion			
6	Chip Remark: X: Length Y: Width		Acceptable criterionXY $\langle L/8$ 0.5mm $\leq t/2$		
	Z: Thickness t: Glass thickness W: Terminal width L: Glass length		Acceptable criterionXY ≤ 2 0.5mm		
		Y X X	XYZ ≤ 3 ≤ 2 $\leq t$ shall not reach to ITO $\leq t$		
		$W_{\underline{y}}$	Acceptable criterionXYZDisregard ≤ 0.2		
		$\begin{array}{c c} & Y \\ & & & & \\ & & & \\ & & & & \\ & & & \\ & & & & \\ & & & & \\ & & & & \\ & & & & \\ & & & & \\ & & & & \\ & & & & \\ & & & & \\ & & & & \\ & & & & \\ & & & & \\ & & & & \\ & & & & \\ &$	Acceptable criterionXYZ ≤ 5 ≤ 2 $\leq t/3$		

No.	Item	Criterion		
7	Segment pattern W = Segment width $\phi = (X+Y)/2$	 (1) Pin hole φ < 0.10mm is acceptable. 		
		YXPoint SizeAcceptable QtyYY $\phi \leq 1/4W$ Disregard1/4W< $\phi \leq 1/2W$ 1 $\phi > 1/2W$ 0Unit: mm		
8	Back-light	 The color of backlight should be in match with the specification. Not allow flickering 		
9	Soldering	 (1) Not allow heavy dirty and solder ball on PCB. (The size of dirty refer to point and dust defect) (2) Over 50% of lead should be soldered on Land. 		
10	Wire	 (1) Copper wire should not be rusted (2) Not allow crack on copper wire connection. (3) Not allow reversing the position of the flat cable. (4) Not allow exposed copper wire inside the flat cable. 		
11*	РСВ	(1) Not allow screw rust or damage.(2) Not allow missing or wrong putting of component.		



Reliability test of LCM

Reliability test condition:

Item	Condition	Time (hrs)	Assessment
High temp. Storage	80°C	48	No abnormalities in functions and appearance
High temp. Operating	70°C	48	
Low temp. Storage	-30°C	48	
Low temp. Operating	-20°C	48	
Humidity	40°C/ 90%RH	48	
Temp. Cycle	$0^{\circ}C \leftarrow 25^{\circ}C \rightarrow 50^{\circ}C$ (30 min \leftarrow 5 min \rightarrow 30min)	10cycles	

Recovery time should be 24 hours minimum.

Precaution for using LCD/LCM

LCD/LCM is assembled and adjusted with a high degree of precision. Do not attempt to make any alteration or modification. The followings should be noted.

General Precautions:

- 1. LCD panel is made of glass. Avoid excessive mechanical shock or applying strong pressure onto the surface of display area.
- 2. The polarizer used on the display surface is easily scratched and damaged. Extreme care should be taken when handling. To clean dust or dirt off the display surface, wipe gently with cotton, or other soft material soaked with isopropyl alcohol or ethyl alcohol, do not use water, ketone or aromatics and never scrub LCD screen hard.
- 3. Do not tamper in any way with the tabs on the metal frame.
- 4. Do not make any modification on the PCB without consulting XIAMEM OCULAR
- 5. When mounting a LCM, make sure that the PCB is not under any stress such as bending or twisting. Elastomer contacts are very delicate and missing pixels could result from slight dislocation of any of the elements.
- 6. Avoid pressing on the metal bezel, otherwise the elastomer connector could be deformed and lose contact, resulting in missing pixels and also cause rainbow on the display.
- 7. Be careful not to touch or swallow liquid crystal that might leak from a damaged cell. Any liquid crystal spreads to skin or clothes, wash it off immediately with soap and water.

Static Electricity Precautions:

- 1. CMOS-LSI is used for the module circuit; therefore, the operators should be grounded whenever he/she comes into contact with the module.
- 2. Do not touch any of the conductive parts such as the LSI pads; the copper leads on the PCB and the interface terminals with any parts of the human body.
- 3. Do not touch the connection terminals of the display with bare hand; it will cause disconnection or defective insulation of terminals.
- 4. The modules should be kept in anti-static bags or other containers resistant to static for storage.
- 5. Only properly grounded soldering irons should be used.

6. If an electric screwdriver is used, it should be grounded and shielded to prevent sparks.

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- 7. The normal static prevention measures should be observed for work clothes and working benches.
- 8. Since dry air is inductive to static, a relative humidity of 50-60% is recommended.

Soldering Precautions:

- 1. Soldering should be performed only on the I/O terminals.
- 2. Use soldering irons with proper grounding and no leakage.
- 3. Soldering temperature: 280°C+10°C
- 4. Soldering time: 3 to 4 second.
- 5. Use eutectic solder with resin flux filling.
- 6. If flux is used, the LCD surface should be protected to avoid spattering flux.
- 7. Flux residue should be removed.

Operation Precautions:

- 1. The viewing angle can be adjusted by varying the LCD driving voltage Vo.
- 2. Since applied DC voltage causes electro-chemical reactions, which deteriorate the display, the applied pulse waveform should be a symmetric waveform such that no DC component remains. Be sure to use the specified operating voltage.
- 3. Driving voltage should be kept within specified range; excess voltage will shorten display life.
- 4. Response time increases with decrease in temperature.
- 5. Display color may be affected at temperatures above its operational range.
- 6. Keep the temperature within the specified range usage and storage. Excessive temperature and humidity could cause polarization degradation, polarizer peel-off or generate bubbles.
- 7. For long-term storage over 40°C is required, the relative humidity should be kept below 60%, and avoid direct sunlight.